

AMENDMENTS TO THE CLAIMS

Please **AMEND** claims 1 and 6 as follows.

This listing of claims will replace all previous versions or listing of claims in the application.

Listing of Claims

1. (Currently Amended) A copper foil with an ultra thin adhesive layer for a printed wiring board comprising a ultra thin primer resin layer of a thickness of 1 to 3 μm provided on a surface of a copper foil, wherein said surface of the copper foil has not undergone a roughening treatment and has a surface roughness (Rz) of less than 2 μm or less, and wherein said ultra thin primer resin layer is formed using a resin mixture consisting of 20 to 80 parts by weight of an epoxy resin that may contain a curing agent, 20 to 80 parts by weight of a solvent-soluble aromatic polyamide resin polymer, and an effective amount of a curing accelerator, and

wherein a resin flow of the ultra-thin primer resin layer when measured in accordance with MIL-P-13949G in the MIL Standard is 5% or less, and for the purpose of the resin flow measurement a thickness of the ultra-thin primer resin layer has been increased to 40 μm .

2. (Original) The copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 1, comprising a silane coupling agent layer on the surface of the copper foil provided with the ultra thin primer resin layer.

3. (Original) The copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 2, wherein said silane coupling agent layer is formed using an amino-based

silane coupling agent or a mercapto-based silane coupling agent.

4. (Cancelled).

5. (Previously Presented) The copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 1, wherein said aromatic polyamide resin polymer using for said ultra thin primer resin layer is obtained by allowing an aromatic polyamide to react with a resin.

6. (Currently Amended) A copper foil with an ultra thin adhesive layer for a printed wiring board comprising a ultra thin primer resin layer of a thickness of 1 to 3 μm provided on a surface of a copper foil, wherein said surface of the copper foil has not undergone a roughening treatment and has a surface roughness (Rz) of less than 2 μm or less, and wherein said ultra thin primer resin layer is formed using a resin mixture consisting of 5 to 50 parts by weight of an epoxy resin that may contain a curing agent, 50 to 95 parts by weight of a polyether sulfone resin, and an appropriate quantity added as required of a curing accelerator, and

wherein a resin flow of the ultra-thin primer resin layer when measured in accordance with MIL-P-13949G in the MIL Standard is 5% or less, and for the purpose of the resin flow measurement a thickness of the ultra-thin primer resin layer has been increased to 40 μm .

7. (Canceled).

8. (Previously Presented) A method for manufacturing a copper foil with an ultra thin adhesive layer for a printed wiring board comprising:

forming a resin mixture by mixing (1) an epoxy resin, which contains a curing agent, (2) an aromatic polyamide polymer soluble in a solvent or a polyether sulfone resin, and (3) an appropriate quantity added as required of a curing accelerator;

dissolving the resin mixture using an organic solvent to form a resin solution of a resin solid content of 10% by weight to 40% by weight;

applying the resin solution onto a surface of a copper foil on which a silane coupling agent layer has been formed to form a resin layer; and

drying the resin layer to a semi cured state,

wherein the thickness of the resin layer is 1 to 3 μm .

9. (Previously Presented) A copper-clad laminate comprising a copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 1.

10. (Previously Presented) A copper-clad laminate comprising a copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 2.

11. (Previously Presented) A copper-clad laminate comprising a copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 3.

12. (Cancelled).

13. (Previously Presented) A copper-clad laminate comprising a copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 5.

14. (Previously Presented) A copper-clad laminate comprising a copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 6.

15. (Canceled).

16. (Previously Presented) The copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 6, wherein the polyether sulfone resin has a hydroxyl group or an amino group at a proximal end, and is soluble in a solvent.

17. (Previously Presented) The copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 6, comprising a silane coupling agent layer on the surface of the copper foil provided with the ultra thin primer resin layer.

18. (Previously Presented) The copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 17, wherein said silane coupling agent layer is formed using an amino-based silane coupling agent or a mercapto-based silane coupling agent.